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causes edges 96 of the metal layer 90 to be aligned with edges 24, 86 of the semiconductor device 12 and the substrate 72.

**In the Claims:**

✓  
Cancel claim 24 without prejudice or disclaimer to the subject matter recited therein.

Rewrite claims 25, 30 and 34 as follows:

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25. (Amended) A semiconductor device package, comprising:  
a semiconductor device having edges formed by a dicing operation;  
a dielectric substrate having edges formed by said dicing operation;  
a metal layer formed between said semiconductor device and said dielectric substrate having edges formed by said dicing operation;  
a ball grid array on said dielectric substrate, said dielectric substrate and said metal layer being located between said semiconductor device and said ball grid array;  
and  
electrical connections between said semiconductor device and said ball grid array.

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30. (Amended) The package of claim 25, wherein said connections comprise wire bonds.

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34. (Amended) The package of claim 25, further comprising an insulative solder mask for covering said dielectric substrate.